

AN-1227 LM3485 Evaluation Board

1 Introduction

The LM3485 is a hysteretic P-FET buck controller that uses a pulse-frequency modulation (PFM) scheme to regulate the output voltage. This LM3485 demo board and the recommended components are intended to demonstrate the performance with a 3.3 V output from a 12 V source. The demo board can be used with source voltages from 7 V to 28 V to deliver output load currents up to 1A. By changing the size of a single resistor, regulated output voltages from 1.242 V to 5 V can be obtained.

The circuit schematic is shown in Figure 1 and the bill of materials is given in Table 1.

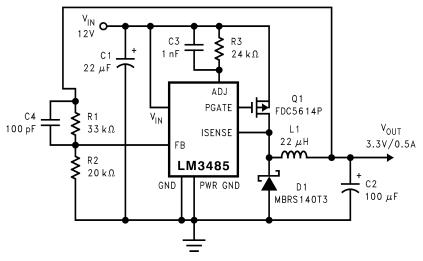


Figure 1. Regulator With 3.3 V Output at 0.5A

| Table 1 | . Bill of | Materials (| (BOM) |
|---------|-----------|-------------|-------|
|---------|-----------|-------------|-------|

| Code | Description | Manufacturer |
|------|---|-------------------|
| C1 | Input Capacitor CAP-Tantalum 22 µF 35 V EEJL1VD226R | Panasonic |
| C2 | Output Capacitor CAP-POSCAP 100 µF 6.3 V 6TPC100M | Sanyo |
| C3 | C _{ADJ} CAP-Ceramic Chip 1nF 50 V GRM39X7R102K50 | Murata |
| C4 | C _{ff} CAP-Ceramic Chip 100pF 50 V GRM39X7R101K50 | Murata |
| D1 | Catch Diode Schottky Diode 1A 30 V MBRS130T3 | On Semiconductor |
| L1 | Inductor 22 µH LQH66SN220M01L | Murata |
| Q1 | P-channel MOSFET -60 V FDC5614P | Fairchild |
| R1 | Feedback high side resistor Chip Resistor 33 K Ω MCR10EZHF3302 | Rohm |
| R2 | Feedback low side resistor Chip Resistor 20 KΩ MCR10EZHF2002 | Rohm |
| R3 | R _{ADJ} Chip Resistor 24KΩ MCR10EZHF2402 | Rohm |
| U1 | Buck Controller LM3485 | Texas Instruments |

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Output Voltage Current Limit Setting

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2 Output Voltage Current Limit Setting

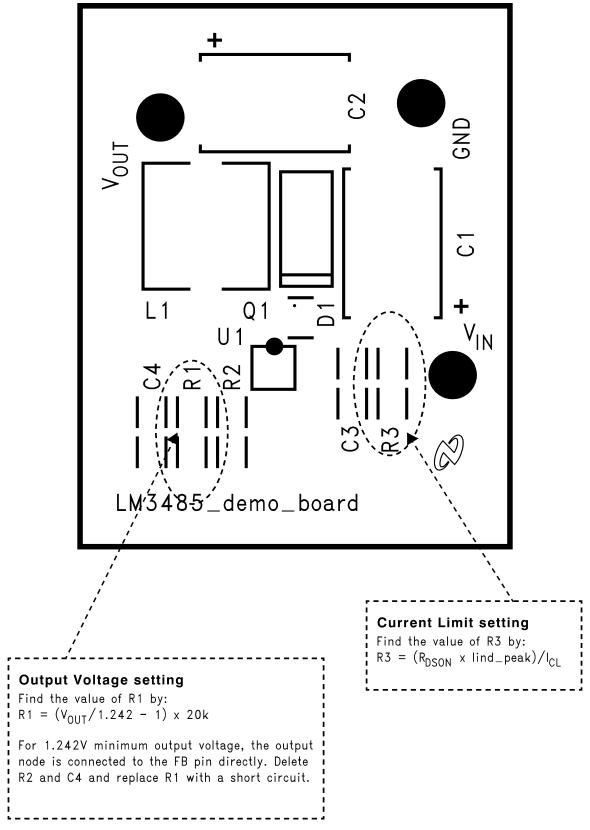


Figure 2. Component Location (Top Side)

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3 Layout Fundamentals

The LM3485 can work in a wide range of applications. For your application circuit, proper layout for the buck regulator should be implemented by following a few simple guidelines.

- 1. Place the power components, which are the MOSFET, diode, inductor and filter capacitors, close together. Make the traces between them as short and as wide as possible.
- 2. Place the trace for the Gate of the external PFET as close as possible to the PGATE pin of the LM3485.
- 3. Separate any noise sensitive traces, primarily in the voltage feedback path, from noise source traces associated with the inductor.
- 4. Keep the trace short between the ground pin of the input capacitor and the anode of the diode.
- 5. Ensure the ground is low impedance.

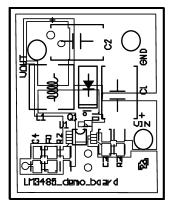


Figure 3. Top Layer

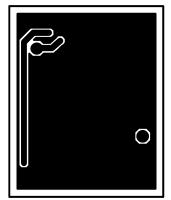


Figure 4. Bottom Layer

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